

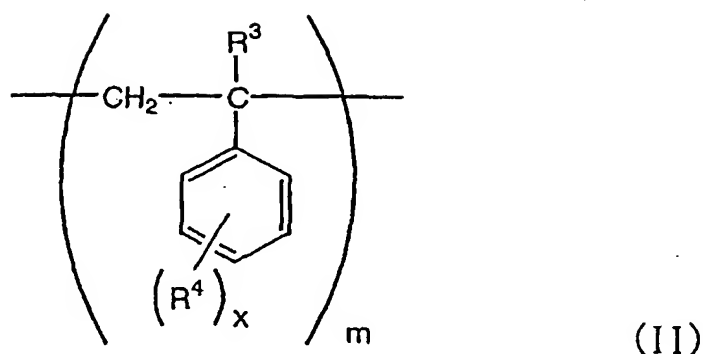
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DT04 Rec'd PCT/PTO 14 OCT 2004

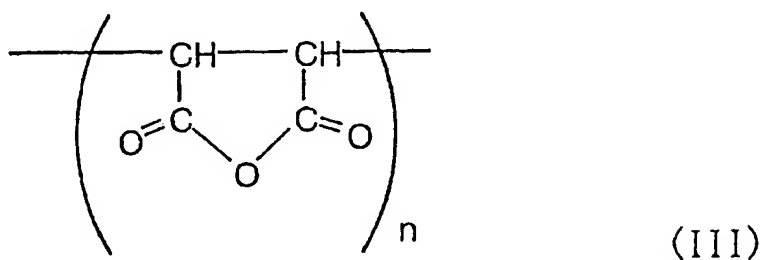
IN THE CLAIMS:

These claims will replace all prior versions of claims in the present application.

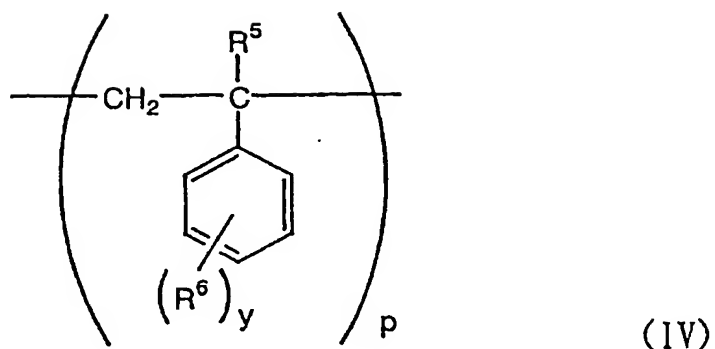
1. (Currently Amended) A thermosetting resin composition ~~containing~~comprising:
  - (1) a metal salt of a ~~bisubstituted~~disubstituted phosphinic acid, and
  - (2) a resin having a dielectric constant of ~~equal to or less than 2.9~~or less at a frequency of 1 GHz or more.
2. (Currently Amended) The thermosetting resin composition ~~as claimed in~~according to claim 1, wherein the dielectric constant of the thermosetting resin composition is ~~equal to or less than 3.0~~or less at a frequency of 1 GHz or more.
3. (Currently Amended) The thermosetting resin composition ~~as claimed in~~according to claim 1 ~~or 2~~, which further ~~contains~~comprises (3) a thermosetting nitrogen atom-containing resin.
4. (Currently Amended) The thermosetting resin composition ~~as claimed in~~according to claim 1 ~~or 2~~, wherein the component (2) is ~~one or more~~at least one resin compositions selected from the group consisting of:  
copolymer resin (2-1) ~~containing~~comprising:  
monomer unit (a) represented by formula (II):



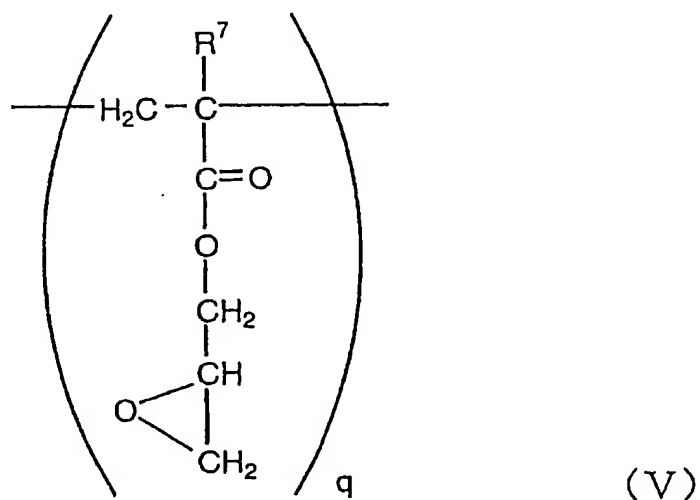
{wherein  $R^3$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms;  $R^4$ s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group;  $x$  is an integer of 0 to 3; and  $m$  is a natural number ~~and~~ representsrepresenting the repeating number of a monomer unit in a copolymer}, and monomer unit (b) represented by formula (III):



{wherein  $n$  is a natural number ~~and representsrepresenting~~ the repeating number of a monomer unit in a copolymer};  
copolymer resin (2-2) ~~containing~~comprising:  
monomer unit (c) represented by formula (IV):

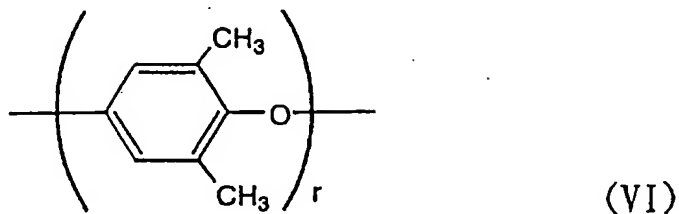


{wherein  $R^5$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms;  $R^6$ s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group;  $y$  is an integer of 0 to 3; and  $p$  is a natural number and ~~represents~~ representing the repeating number of a monomer unit in a copolymer}, and monomer unit (d) represented by formula (V):



{wherein  $R^7$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and  $q$  is a natural number and ~~represents~~ representing the repeating number of a monomer unit in a copolymer}; and resin (2-3) ~~containing~~ comprising:

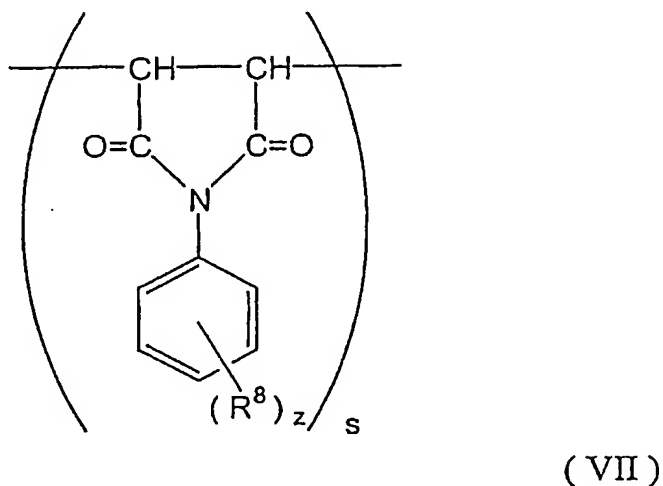
monomer unit (e) represented by formula (VI):



{wherein r is a natural number ~~and represents~~representing the repeating number of a monomer unit in a copolymer}.

5. (Currently Amended) The thermosetting resin composition ~~as claimed in~~according to claim 4, wherein the copolymer resin (2-1) is a copolymer resin further ~~containing~~comprising:

monomer unit (f) represented by the following formula (VII):



{wherein R<sup>8</sup> is a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group, a hydroxyl group, a thiol group or a carboxyl group; z is an integer of 0 to 3; and s is a natural number ~~and represents~~representing the repeating number of a monomer unit in a copolymer}.

6. (Currently Amended) The thermosetting resin composition ~~as claimed in~~according to claim 1 ~~or 2~~, which further ~~contains~~comprises (4) an epoxy resin.

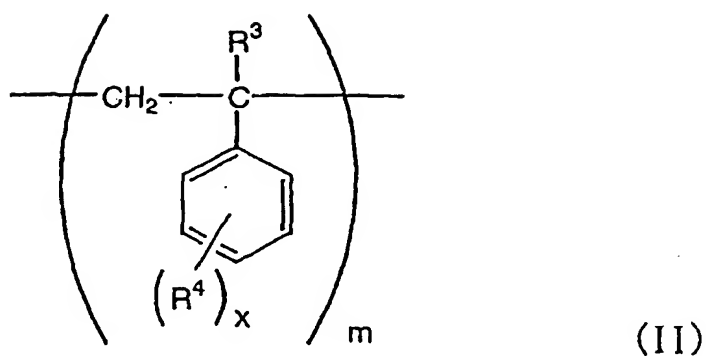
7. (Currently Amended) A prepreg using the thermosetting resin composition ~~claimed in~~according to any one of claims 1 to 6 claim 1.

8. (Currently Amended) A ~~laminated sheet~~laminated board obtained by using and laminate molding ~~using the prepreg claimed in~~according to claim 7.

9. (Currently Amended) A thermosetting resin composition ~~containing~~comprising a metal salt of a ~~bisubstituted~~disubstituted phosphinic acid, wherein a dielectric constant of the composition is ~~equal to or less than 3.0~~ or less at a frequency of 1 GHz or more.

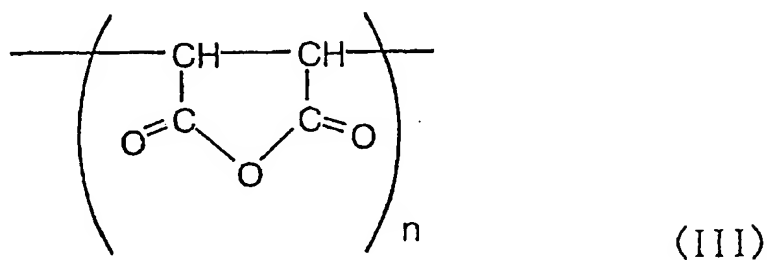
10. (New) The thermosetting resin composition according to claim 2, which further comprises (3) a thermosetting nitrogen atom-containing resin.

11. (New) The thermosetting resin composition according to claim 2, wherein the component (2) is at least one resin compositions selected from the group consisting of: copolymer resin (2-1) comprising:  
monomer unit (a) represented by formula (II):



wherein  $R^3$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms;  $R^4$ s are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group;  $x$  is an integer of 0 to 3; and  $m$  is a natural number representing the repeating number of a monomer unit in a copolymer, and

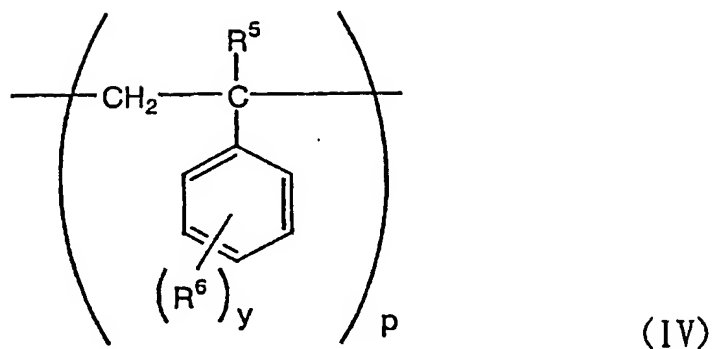
monomer unit (b) represented by formula (III):



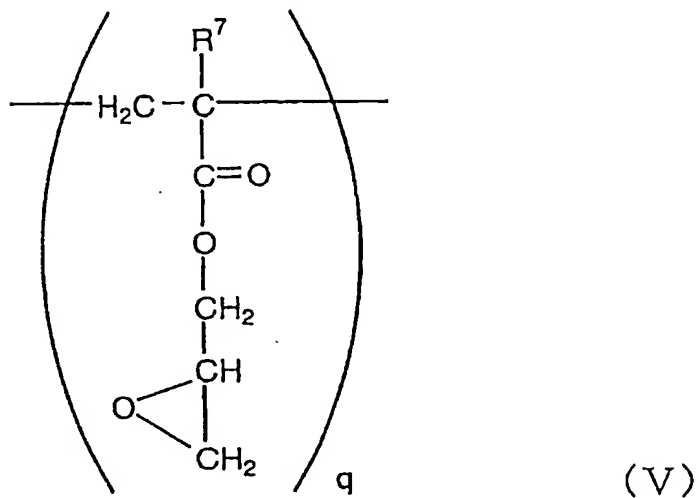
wherein  $n$  is a natural number representing the repeating number of a monomer unit in a copolymer;

copolymer resin (2-2) comprising:

monomer unit (c) represented by formula (IV):

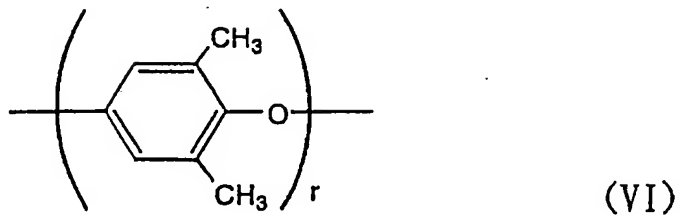


wherein  $R^5$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms;  $R^6$ 's are each independently a halogen atom, an aliphatic hydrocarbon group having 1 to 5 carbon atoms, an aromatic hydrocarbon group or a hydroxyl group;  $y$  is an integer of 0 to 3; and  $p$  is a natural number and representing the repeating number of a monomer unit in a copolymer, and monomer unit (d) represented by formula (V):



wherein  $R^7$  is a hydrogen atom, a halogen atom or a hydrocarbon group having 1 to 5 carbon atoms; and  $q$  is a natural number representing the repeating number of a monomer unit in a copolymer; and resin (2-3) comprising:

monomer unit (e) represented by formula (VI):



wherein r is a natural number representing the repeating number of a monomer unit in a copolymer.

12. (New) The thermosetting resin composition according to claim 2, which further comprises (4) an epoxy resin.